300mm Fully-Automatic LC Tape Laminator

RAD-3600F/12

- Fully-automatic LC Tape laminator which laminates Adwill LC Tape to wafer backside after back grinding.
- Performs the following functions:
  - Wafer alignment
  - LC Tape pre-cutting
  - LC Tape lamination
  - Release liner peeling

Options:
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- Double Cassette Loading
- Water ID Reader

Suitable Tape:
- Backside coating tape: Adwill LC Tape

Outline

Facility

- Power Supply
  - Voltage: AC200-230V ±10% (AC190-253V)
  - Frequency: 50/60Hz
  - Phase: single phase
  - Power consumption: 6.0kW

- Air Supply
  - Air pressure: 0.5-0.8MPa
  - Air consumption: >150L/min (ANR)

- Vacuum Supply
  - Vacuum pressure: >-80kPa

Applicable Wafer Size
- 200mm, 300mm

Size
- Width: 1,550mm
- Depth: 1,950mm
- Height: 1,800mm
  (excluding the signal tower and protruding parts)

Weight
- 1,500kg

UPH
- 30 wafers/hour (excludes setting time)

The above processing capacity is based on the following conditions:
- Wafer: 300mm diameter non-polished mirror wafer
- LC Tape: LC2850(40) from LINTEC

Specifications

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Contact:
- Advanced Materials Operations
- 2-1-2 Kozaki, Bunkyo-ku, Tokyo 112-0004, Japan
- TEL. +81-3-3868-7737  FAX. +81-3-3868-7726
- E-mail: adwill@lintec.co.jp
- http://www.lintec-global.com/